

770252-2 Product Details - TE

- Multiple Contact Types = Without
- Contact Plating, Mating Area, Thickness (µm [µin]) = 0.76
- [29.92]
- Underplate Material = Nickel

Other: • Brand = AMP

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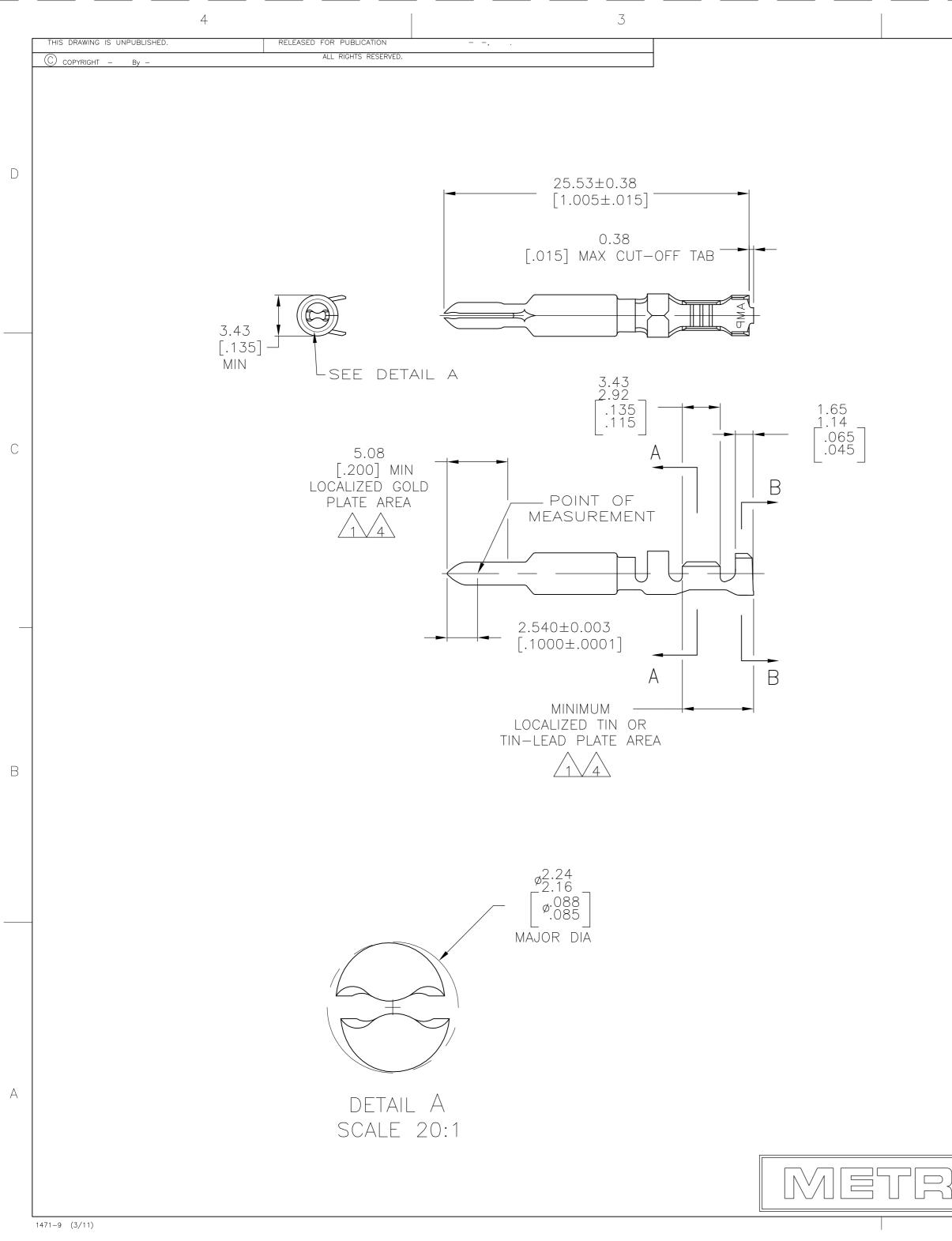
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	LOC DIST REVISIONS CM OO P LTR DESCRIPTION F1 REVISED PER ECO-11-005027	date dwn apvd 11mar11 RK HMR
2.	0.00076[.000030] MIN GOLD AT POINT OF MEASUREMENT IN THE LOCALIZED GOLD P AREA, 0.00127[.000050] MIN TIN-LEAD IN TIN-LEAD PLATE AREA, 0.00127[.000050] NICKEL UNDERPLATE ON ENTIRE CONTACT. WIRE RANGE: 0.2-1mm ² [24-18 AWG]. INSULATION RANGE: 1.02-2.54 [.040100] DIMENSIONS IN BRACKETS ARE IN INCHES 0.00076[.000030] MIN GOLD AT POINT OF MEASUREMENT IN THE LOCALIZED GOLD P AREA, 0.00127[.000050] MIN TIN IN TIN PLATE AREA, 0.00127[.000050] MIN NICKEL UNDERPLATE ON ENTIRE CONTACT.	PLATE MIN DIA. S. F LATE
	NICKEL ONDERN EATE ON ENTITE CONTACT.	C
2.54 2.54 2.16 (100) (.085) REF SECTION A-A SCALE 10:1	3.56 3.18 140 125 (145 130 REF REF SECTION B-B SCALE 10:1	B 770252
THIS DRAWING IS A CONTROLLED DO DIMENSIONS: TOLERANCES mm [INCHES] 0 PLC ± - 1 PLC ± - 2 PLC ± - 2 PLC ± - 4 PLC ± - ANGLES - MATERIAL FINISH	CUMENT. DWN 30SEP04 K. WHITAKER CHK 30SEP04 CLONES TE CC	(TM) II RESTRICTED TO